Solder wire IF 1000M **SnPb(Ag)**

Rosin based, activated no-clean solder wire

Description:

Interflux® **IF 1000M SnPb(Ag)** is a no-clean solder wire that has been developed to give increased wetting on surfaces that are difficult to solder, e.g. OSP, Ni, Zn, messing, German silver,...

The solder wire contains a colophony based body that has been designed to enhance spreading of the solder on solderable surfaces.

IF 1000M SnPb(Ag) is useable in both hand soldering and automated soldering processes.

Depending on the temperature settings, residues can vary from transparent to amber.

The solder wire contains halogens and is classified as RO L1 according to IPC and EN-standards.

Products pictured may differ from the product delivered

Availability

Flux type: IF 1000M
Flux content: 1,0% - 2,2 % w/w

alloy	melting point	diameters 0,35	0,50	0,70	1,00	1,50	2,00
Sn60Pb40	183°C—191°C	●	●	●	●	●	●
Sn63Pb37	183°C	●	●	●	●	●	●

● = available ● = upon request

More information:

Key advantages:

- Increased wetting properties on surfaces that are difficult to solder
- Suitable for automated soldering
- RO L1

S.A. INTERFLUX® ELECTRONICS S N.V. - Eddastraat 51 BE-9042 Gent Belgium
tel.: +32 9251 49 59 - fax.: +32 9251 49 70
info@interflux.com - www.interflux.com

Work instructions

Manual soldering

The advised working temperature is between 320°C and 360°C. For more dense metals like Nickel, the temperature may be elevated to 400°C.

The use of a good soldering station is important. Use a soldering station with a short response time and with enough power for your application.
Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact area with the surfaces to be soldered.
Heat up both the surfaces simultaneously. Slightly touch with the solder wire, the point where soldering tip and the surfaces to be soldered meet (the small quantity of solder ensures a drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip. This will reduce the risk on flux spitting and premature flux consumption!

Handling

Storage

Store the solder wire in a clean environment at ambient temperature.

Handling

To avoid spool and wire damage, handle package with care.

Safety

Please always consult the safety datasheet of the product.

Test results

conform EN 61190-1-3(2007) and IPC J-STD-004(A)

Property	Result	Method
Chemical		
flux designator	**RO L1**	J-STD-004A
	F-SW 26	DIN 8511
	1.1.2	ISO 9454
qualitative copper mirror	**passed**	J-STD-004A IPC-TM-650 2.3.32
% halide content	**< 0,5%**	
acid value	**210 ±30 mg KOH/g**	J-STD-004A 2.3.13
visual	**pass**	J-STD-004 Ref. paragraph 3.5.4
Environmental		
SIR test	**pass**	J-STD-004 IPC-TM-650 2.6.3.3
qualitative corrosion, flux	**pass**	J-STD-004A IPC-TM-650 2.6.15
electro chemical migration	**pass**	J-STD-004A IPC-TM-650 2.6.14.1

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Packaging

Spools of 100g, 500g and 1000g

Trade name: IF 1000M leaded, rosin based, activated no-clean solder wire

D i s c l a i m e r

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